Chip Scale REVIEW

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# BiTS' Arizona Workshop Draws Record Attendance

The 5th annual Burn-in & Test Socket Workshop (BiTS), held March 7-10 in Mesa, Arizona, drew a record attendance of 320, a 50 percent year-to-year increase.

The technical program featured a panel discussion, keynote speaker and 25 presentations spread across eight sessions. Complementing the technical program was an exhibit area that attracted 34 companies that displayed their products or discussed their services with attendees.

The attendees and exhibitors represented end users and suppliers of sockets, boards, burn-in systems, test systems, handlers, packaging technology, materials and other related equipment and services. Additionally, numerous networking opportunities provided further opportunities to learn and share ideas with colleagues in an informal environment.

Fred Taber, general chair, noted that "BiTS' clearly fills an industry need."

Sharing a collection of user experiences, Jon Diller of Synergetix opened the panel discussion topic of "Making It All Work Together: Interface Challenges and Solutions" paper: "Obstacles In the Transfer of Contactor Solutions from the OEM to the Subcontractor."

Five other panelists offered their views on interfacing challenges and possible solutions to achieve a successful integration of the load board, change kit/nest, docking hardware, handler, contactor, test head, and the package to meet the end customer's requirements. This was followed by a lively Q&A session with the audience that centered around who "owns" the integration responsibility. Suggestions for increased collaboration among the suppliers highlighted the discussion.

Keynote speaker David Johnson, Founder, CEO and President of Johnstech International Corp., Minneapolis, discussed "Helping Customers Improve Their Performance Results." His talk encouraged more collaboration and sharing across the socketing community. The discussion led to plans by a group in the audience to explore and define "best known methods" for determining some key socketing parameters.

Twenty-five papers were presented in eight technical sessions. Awards presented included "Best Paper" to Tim Swettlen, Intel; Eric Bogatin, Synergetix; Gary Otonari, GigaTest Labs and Orlando Bell, also of GigaTest Labs for the paper, "A Method for Contactor Characterization to 25 GHz."

The Most Inspirational Paper award went to Qifang "Michelle" Qiao of IBM Microelectronics and Karl Schoenfeld of Gonzer Associates for "Current Rating For Contacts-Time to Standardize the Test Method."

*-Contributed by BiTS*

Exhibitors included (in alphabetical order):

AEHR Test Systems, Fremont, Calif.; Altanova, San Jose; Ardent Concepts Inc., Hampton, N.H.; Aries Electronics, Frenchtown, N.J.; Azimuth Electronics, San Clemente, Calif.; Brush Wellman, Cleveland, Ohio; Dimensions Consulting Inc., Santa Clara, Calif.; Enplas Tesco Inc., Sunnyvale, Calif.; Everett Charles Technologies, Pomona, Calif.; Gold Technologies, San Jose; High Connection Density, Sunnyvale, Calif.; Ironwood Electronics, Eagan, Minn.; Incal Technology, Milpitas, Calif.; Johnstech International Corp., Minneapolis, Minn.; Kulicke & Soffa Industries, Willow Grove, Pa.; Micro Control Co., Minneapolis, Minn.; Micronics Japan Co., Tokyo; Nikon Instruments Inc., Melville, N.Y.; Paricon Technologies Corp., Fall River, Mass.; Phoenix Test Arrays, Phoenix; Piper Plastics Inc., Chandler, Ariz.; Plastronics Socket Co., Irving, Texas; Rika Denshi America, Attleboro, Mass.; RS Tech Inc., Phoenix, Ariz.; Synergetix, Kansas City, Kansas; Tecknit Interconnection Products, Crawford, N.J., Texas Instruments, Attleboro, Mass.; 3M Company, Austin, Texas; Unisys Corp., Chandler, Ariz.; Wells-CTI, Phoenix, Ariz., and Yamaichi Electronics, San Jose.